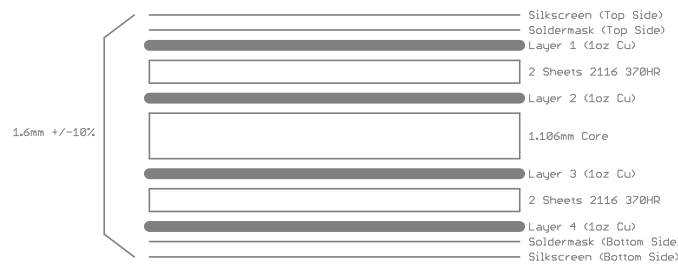


PCB Fabrication Notes

- 1) Board material shall be 370HR with UL 94V-0 rating.
- 2) Inner and outer copper shall be 1oz (reference stackup)
- 3) Red soldermask with white silkscreen. Specifics not specified
Exposed traces are unacceptable
- 4) Exposed conductive patterns not covered in soldermask or plated shall be finished via lead free silver immersion
- 5) PCB shall be fabricated in accordance with IPC-6012 Class 2 using supplied data files
- 6) Hole sizes refer to finished hole size
- 7) All holes shall have a tolerance of $\pm 0.0762\text{mm}$
- 8) If teething is required, it shall have a clearance greater than 8mm from all design features
- 9) The only required PCB marking is a 94V-0 stamp.
All others are at the fabricators discretion

Sym	N°	Mils	MM	Qty	Plated
+	1	8	0.20	154	YES
X	2	12	0.30	1	YES
□	3	16	0.40	184	YES
◇	4	18	0.46	133	YES
⊗	5	20	0.50	2	YES
⊗	6	24	0.60	4	YES
⊕	7	28	0.70	11	YES
⊕	8	32	0.81	4	YES
✖	9	40	1.02	32	YES
✖	10	47	1.19	2	YES
▽	11	55	1.40	4	YES
△	12	79	2.00	2	YES
↖	13	118	3.00	4	BOTH
▷	14	197	5.00	1	YES

PCB Stackup



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